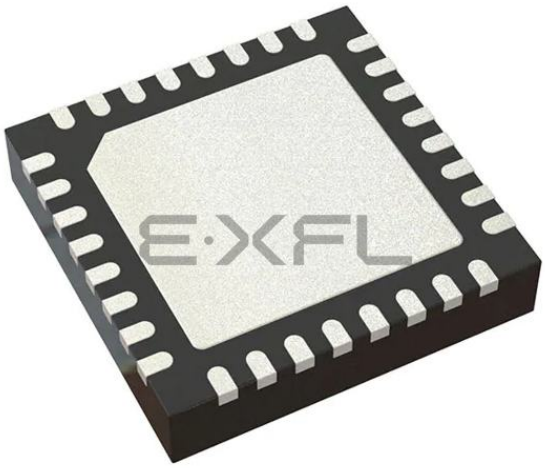


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

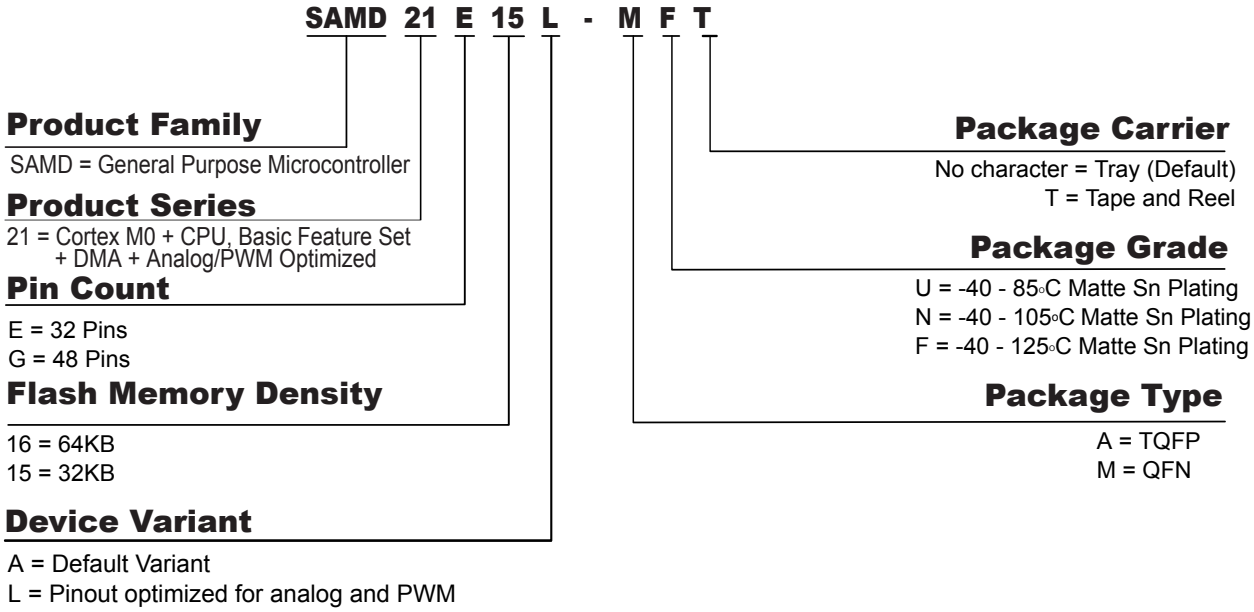
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	26
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 10x12b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-VQFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atsamd21e15l-mf

        - Up to four compare channels with optional complementary output
        - Generation of synchronized pulse width modulation (PWM) pattern across port pins
        - Deterministic fault protection, fast decay and configurable dead-time between complementary output
        - Dithering that increase resolution with up to 5 bit and reduce quantization error
    - 32-bit Real Time Counter (RTC) with clock/calendar function
    - Watchdog Timer (WDT)
    - CRC-32 generator
    - Up to six Serial Communication Interfaces (SERCOM), each configurable to operate as either:
        - USART with full-duplex and single-wire half-duplex configuration
        - I^2C up to 3.4MHz
        - SPI
        - LIN slave
    - One 12-bit, 350ksps Analog-to-Digital Converter (ADC) with up to 18 channels
        - Differential and single-ended input
        - 1/2x to 16x programmable gain stage
        - Automatic offset and gain error compensation
        - Oversampling and decimation in hardware to support 13-, 14-, 15- or 16-bit resolution
    - 10-bit, 350ksps Digital-to-Analog Converter (DAC)
    - Four Analog Comparators (AC) with window compare function
- I/O
    - Up to 38 programmable I/O pins
- Packages
    - 48-pin TQFP, QFN
    - 32-pin QFN
- Operating Voltage
    - 1.62V – 3.63V

3. Ordering Information



3.1 SAM D21ExL

Ordering Code	FLASH (bytes)	SRAM (bytes)	Temperature Range	Package	Carrier Type
ATSAMD21E15L-MNT	32K	4K	105°C	QFN32	Tape & Reel
ATSAMD21E15L-MFT	32K	4K	125°C	QFN32	Tape & Reel
ATSAMD21E15L-AFT	32K	4K	125°C	TQFP32	Tape & Reel
ATSAMD21E16L-MNT	64K	8K	105°C	QFN32	Tape & Reel
ATSAMD21E16L-MFT	64K	8K	125°C	QFN32	Tape & Reel
ATSAMD21E16L-AFT	64K	8K	125°C	TQFP32	Tape & Reel

3.2 SAM D21GxL

Ordering Code	FLASH (bytes)	SRAM (bytes)	Temperature Range	Package	Carrier Type
ATSAMD21G16L-MUT	64K	8K	85°C	QFN48	Tape & Reel
ATSAMD21G16L-MNT	64K	8K	105°C	QFN48	Tape & Reel

3.3 Device Identification

The DSU - Device Service Unit peripheral provides the Device Selection bits in the Device Identification register (DID.DEVSEL) in order to identify the device by software. The SAM D21L variants have a reset value of DID=0x1001drxx, with the LSB identifying the die number ('d'), the die revision ('r') and the device selection ('xx').

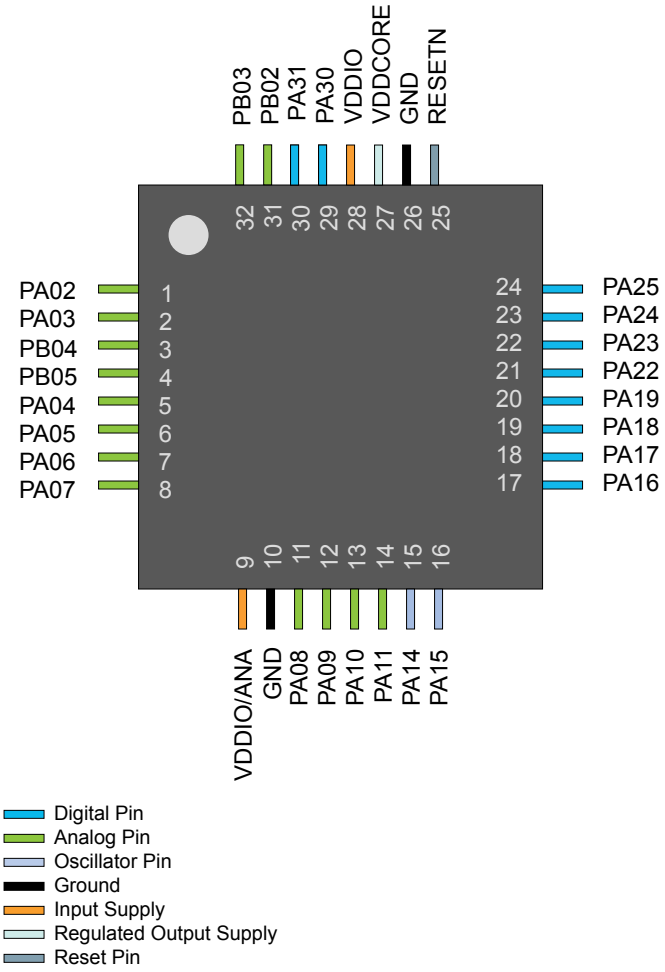
Table 3-1. SAM D21L Device Identification Values

Device Variant	DID.DEVSEL	Device ID (DID)
Reserved	0x00 - 0x61	
SAMD21E16L	0x62	0x1001143E
SAMD21E15L	0x63	0x1001143F
Reserved	0x64 - 0x86	
SAMD21G16L	0x87	0x10011457
Reserved	0x88 - 0xFF	

Note: The device variant (last letter of the ordering number) is independent of the die revision (DSU.DID.REVISION): The device variant denotes functional differences, whereas the die revision marks evolution of the die. The device variant denotes functional differences, whereas the die revision marks evolution of the die.

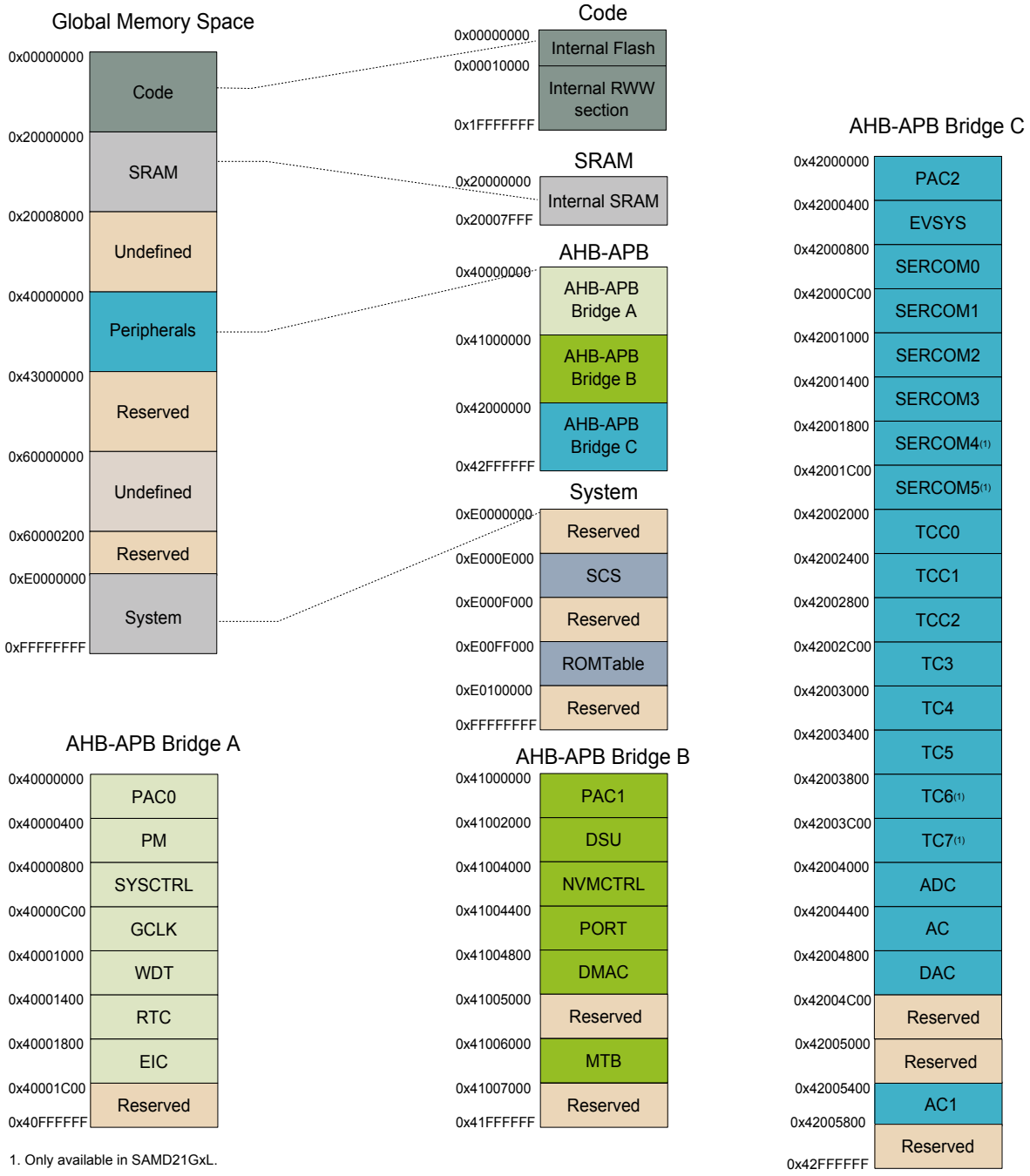
5.2 SAM D21ExL

5.2.1 QFN32 / TQFP32



6. Product Mapping

Figure 6-1. SAM D21L Product Mapping



1. Only available in SAMD21GxL.

This figure represents the full configuration of the SAM D21L with maximum flash and SRAM capabilities and a full set of peripherals. Refer to the configuration summary for details.

7. Processor And Architecture

7.1 Cortex M0+ Processor

The SAM D21L implements the ARM® Cortex®-M0+ processor, based on the ARMv6 Architecture and Thumb®-2 ISA. The Cortex M0+ is 100% instruction set compatible with its predecessor, the Cortex-M0 core, and upward compatible to Cortex-M3 and M4 cores. The ARM Cortex-M0+ implemented is revision r0p1. For more information refer to http://www.arm.com.

7.1.1 Cortex M0+ Configuration

Table 7-1. Cortex M0+ Configuration

Features	Configurable option	Device configuration
Interrupts	External interrupts 0-32	28
Data endianness	Little-endian or big-endian	Little-endian
SysTick timer	Present or absent	Present
Number of watchpoint comparators	0, 1, 2	2
Number of breakpoint comparators	0, 1, 2, 3, 4	4
Halting debug support	Present or absent	Present
Multiplier	Fast or small	Fast (single cycle)
Single-cycle I/O port	Present or absent	Present
Wake-up interrupt controller	Supported or not supported	Not supported
Vector Table Offset Register	Present or absent	Present
Unprivileged/Privileged support	Present or absent	Absent(1)
Memory Protection Unit	Not present or 8-region	Not present
Reset all registers	Present or absent	Absent
Instruction fetch width	16-bit only or mostly 32-bit	32-bit

Note:

1. All software run in privileged mode only.

The ARM Cortex-M0+ core has two bus interfaces:

- Single 32-bit AMBA-3 AHB-Lite system interface that provides connections to peripherals and all system memory, which includes flash and RAM.
- Single 32-bit I/O port bus interfacing to the PORT with 1-cycle loads and stores.

7.1.2 Cortex-M0+ Peripherals

- System Control Space (SCS)
  - The processor provides debug through registers in the SCS. Refer to the Cortex-M0+ Technical Reference Manual for details (www.arm.com).
- System Timer (SysTick)

Peripheral Source	NVIC Line
AC – Analog Comparator	24
DAC – Digital-to-Analog Converter	25
Reserved	26
Reserved	27

7.3 Micro Trace Buffer

7.3.1 Features

- Program flow tracing for the Cortex-M0+ processor
- MTB SRAM can be used for both trace and general purpose storage by the processor
- The position and size of the trace buffer in SRAM is configurable by software
- CoreSight compliant

7.3.2 Overview

When enabled, the MTB records changes in program flow, reported by the Cortex-M0+ processor over the execution trace interface shared between the Cortex-M0+ processor and the CoreSight MTB-M0+. This information is stored as trace packets in the SRAM by the MTB. An off-chip debugger can extract the trace information using the Debug Access Port to read the trace information from the SRAM. The debugger can then reconstruct the program flow from this information.

The MTB simultaneously stores trace information into the SRAM, and gives the processor access to the SRAM. The MTB ensures that trace write accesses have priority over processor accesses.

The execution trace packet consists of a pair of 32-bit words that the MTB generates when it detects the processor PC value changes non-sequentially. A non-sequential PC change can occur during branch instructions or during exception entry. See the CoreSight MTB-M0+ Technical Reference Manual for more details on the MTB execution trace packet format.

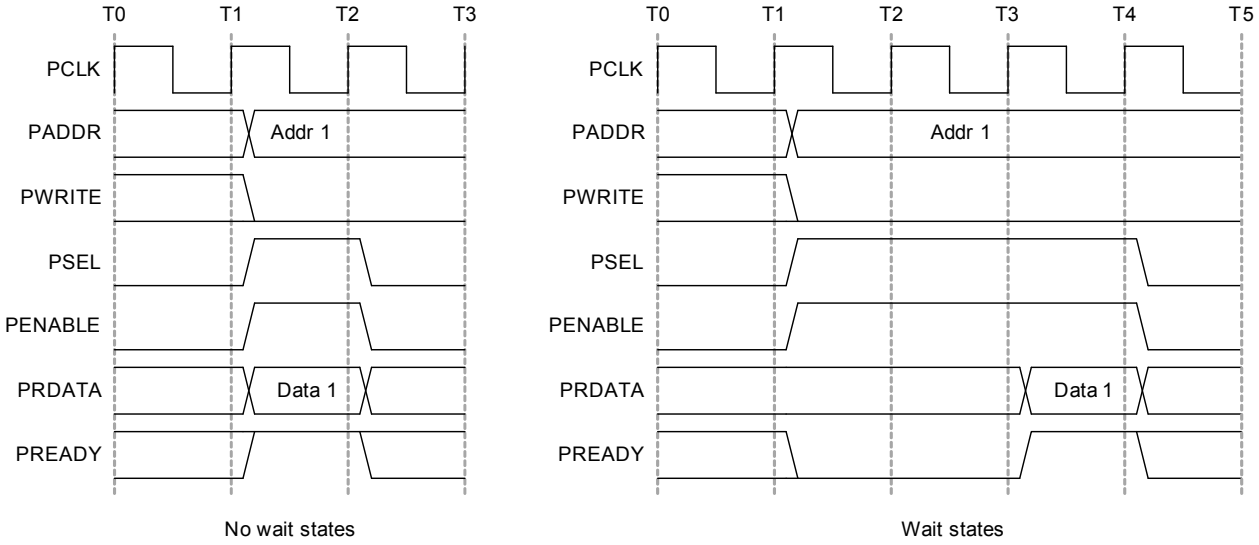
Tracing is enabled when the MASTER.EN bit in the Master Trace Control Register is 1. There are various ways to set the bit to 1 to start tracing, or to 0 to stop tracing. See the CoreSight Cortex-M0+ Technical Reference Manual for more details on the Trace start and stop and for a detailed description of the MTB's MASTER register. The MTB can be programmed to stop tracing automatically when the memory fills to a specified watermark level or to start or stop tracing by writing directly to the MASTER.EN bit. If the watermark mechanism is not being used and the trace buffer overflows, then the buffer wraps around overwriting previous trace packets.

The base address of the MTB registers is 0x41006000; this address is also written in the CoreSight ROM Table. The offset of each register from the base address is fixed and as defined by the CoreSight MTB-M0+ Technical Reference Manual. The MTB has 4 programmable registers to control the behavior of the trace features:

- POSITION: Contains the trace write pointer and the wrap bit,
- MASTER: Contains the main trace enable bit and other trace control fields,
- FLOW: Contains the WATERMARK address and the AUTOSTOP and AUTOHALT control bits,
- BASE: Indicates where the SRAM is located in the processor memory map. This register is provided to enable auto discovery of the MTB SRAM location, by a debug agent.

See the CoreSight MTB-M0+ Technical Reference Manual for a detailed description of these registers.

Figure 7-2. APB Read Access.



Related Links

Product Mapping

7.6 PAC - Peripheral Access Controller

7.6.1 Overview

There is one PAC associated with each AHB-APB bridge. The PAC can provide write protection for registers of each peripheral connected on the same bridge.

The PAC peripheral bus clock (CLK_PACx_APB) can be enabled and disabled in the Power Manager. CLK_PAC0_APB and CLK_PAC1_APB are enabled are reset. CLK_PAC2_APB is disabled at reset. Refer to *PM – Power Manager* for details. The PAC will continue to operate in any sleep mode where the selected clock source is running. Write-protection does not apply for debugger access. When the debugger makes an access to a peripheral, write-protection is ignored so that the debugger can update the register.

Write-protect registers allow the user to disable a selected peripheral's write-protection without doing a read-modify-write operation. These registers are mapped into two I/O memory locations, one for clearing and one for setting the register bits. Writing a one to a bit in the Write Protect Clear register (WPCLR) will clear the corresponding bit in both registers (WPCLR and WPSET) and disable the write-protection for the corresponding peripheral, while writing a one to a bit in the Write Protect Set (WPSET) register will set the corresponding bit in both registers (WPCLR and WPSET) and enable the write-protection for the corresponding peripheral. Both registers (WPCLR and WPSET) will return the same value when read.

If a peripheral is write-protected, and if a write access is performed, data will not be written, and the peripheral will return an access error (CPU exception).

The PAC also offers a safety feature for correct program execution, with a CPU exception generated on double write-protection or double unprotection of a peripheral. If a peripheral n is write-protected and a write to one in WPSET[n] is detected, the PAC returns an error. This can be used to ensure that the application follows the intended program flow by always following a write-protect with an unprotect, and vice versa. However, in applications where a write-protected peripheral is used in several contexts, e.g., interrupts, care should be taken so that either the interrupt can not happen while the main application or other interrupt levels manipulate the write-protection status, or when the interrupt handler needs to unprotect the peripheral, based on the current protection status, by reading WPSET.

7.6.2 Register Description

Atomic 8-, 16- and 32-bit accesses are supported. In addition, the 8-bit quarters and 16-bit halves of a 32-bit register, and the 8-bit halves of a 16-bit register can be accessed directly. Refer to the Product Mapping for PAC locations.

7.6.2.1 PAC0 Register Description

Write Protect Clear

Name: WPCLR
Offset: 0x00
Reset: 0x000000
Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
Access								
Reset								

Bit	15	14	13	12	11	10	9	8
Access								
Reset								

Bit	7	6	5	4	3	2	1	0
		EIC	RTC	WDT	GCLK	SYSCTRL	PM	
Access		R/W	R/W	R/W	R/W	R/W	R/W	
Reset		0	0	0	0	0	0	

Bit 6 – EIC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 5 – RTC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – PM
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

7.6.2.2 PAC1 Register Description

Write Protect Clear

Name: WPCLR
Offset: 0x00
Reset: 0x000002
Property: –

Bit	31	30	29	28	27	26	25	24
Access								
Reset								

Bit	23	22	21	20	19	18	17	16
Access								
Reset								

Bit	15	14	13	12	11	10	9	8
Access								
Reset								

Bit	7	6	5	4	3	2	1	0
		MTB			PORT	NVMCTRL	DSU	
Access		R/W			R/W	R/W	R/W	
Reset		0			0	0	1	

Bit 6 – MTB
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 3 – PORT
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Bit	15	14	13	12	11	10	9	8
	TC7	TC4	TC5	TC4	TC3	TCC2	TCC1	TCC0
Access	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
Reset	0	0	0	0	0	0	0	0

Bit	7	6	5	4	3	2	1	0
							EVSYS	
Access							R/W	
Reset							0	

Bit 18 – DAC:
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 17 – AC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 16 – ADC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 11, 12, 13, 14, 15 – TC3, TC4, TC5, TC4, TC7
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 8, 9, 10 – TCCn
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 17 – AC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 16 – ADC
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 11, 12, 13, 14, 15 – TC3, TC4, TC5, TC6, TC7
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 8, 9, 10 – TCCn
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bits 2, 3, 4, 5, 6, 7 – SERCOMn
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

Bit 1 – EVSYS
Writing a zero to these bits has no effect.

Writing a one to these bits will clear the Write Protect bit for the corresponding peripherals.

Value	Description
0	Write-protection is disabled.
1	Write-protection is enabled.

8. Packaging Information

8.1 Thermal Considerations

Related Links

Junction Temperature

8.1.1 Thermal Resistance Data

The following Table summarizes the thermal resistance data depending on the package.

Table 8-1. Thermal Resistance Data

Package Type	θ_{JA}	θ_{JC}
32-pin TQFP	64.7°C/W	23.1°C/W
32-pin QFN	40.9°C/W	15.2°C/W
48-pin QFN	32.0°C/W	10.9°C/W

8.1.2 Junction Temperature

The average chip-junction temperature, T_J, in °C can be obtained from the following:

1. $T_J = T_A + (P_D \times \theta_{JA})$
2. $T_J = T_A + (P_D \times (\theta_{HEATSINK} + \theta_{JC}))$

where:

- θ_{JA} = Package thermal resistance, Junction-to-ambient (°C/W), see Thermal Resistance Data
- θ_{JC} = Package thermal resistance, Junction-to-case thermal resistance (°C/W), see Thermal Resistance Data
- $\theta_{HEATSINK}$ = Thermal resistance (°C/W) specification of the external cooling device
- P_D = Device power consumption (W)
- T_A = Ambient temperature (°C)

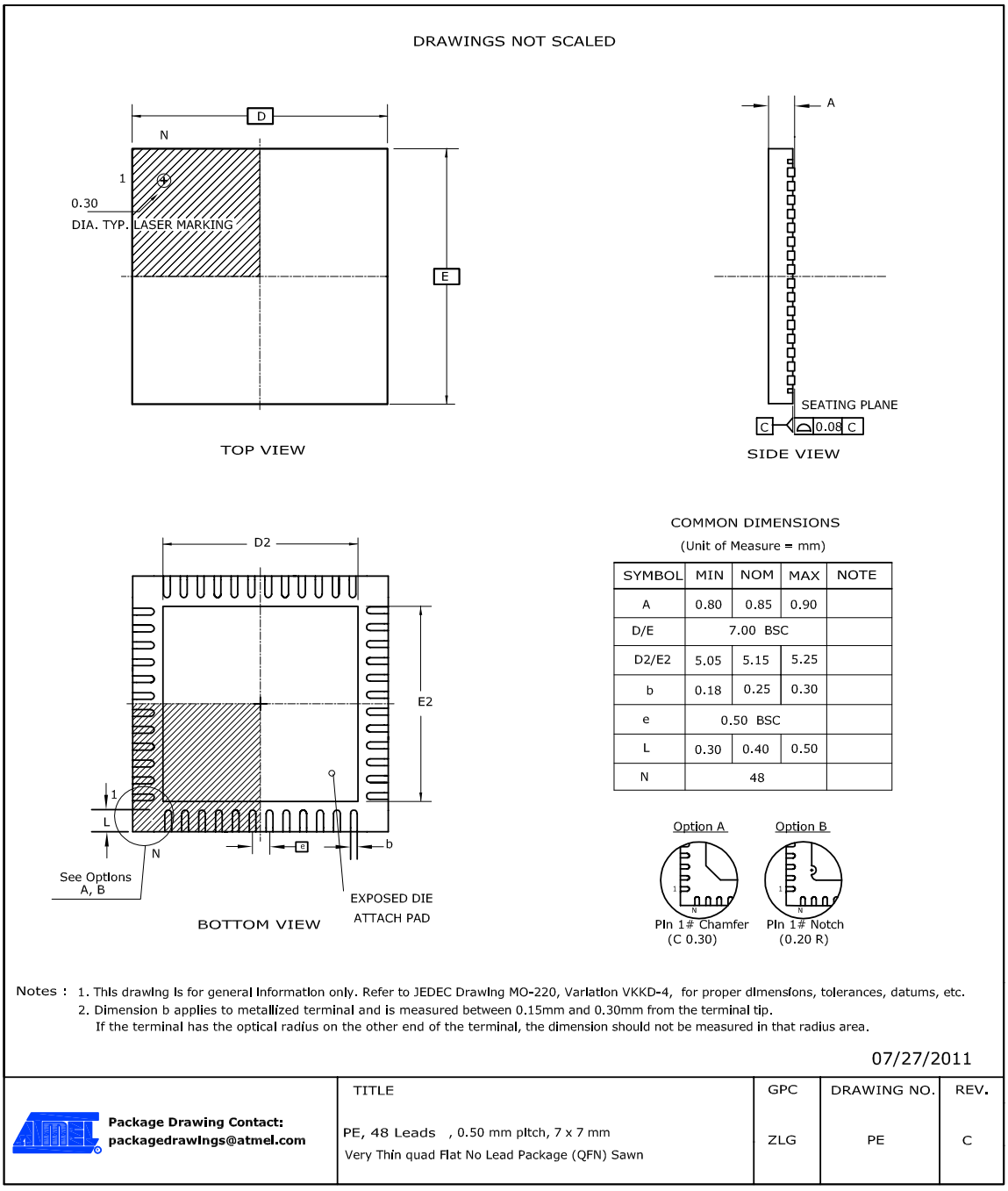
From the first equation, the user can derive the estimated lifetime of the chip and decide if a cooling device is necessary or not. If a cooling device is to be fitted on the chip, the second equation should be used to compute the resulting average chip-junction temperature T_J in °C.

Related Links

Thermal Considerations

8.2 Package Drawings

8.2.1 48 pin QFN



Note: The exposed die attach pad is not connected electrically inside the device.

Table 8-2. Device and Package Maximum Weight

140	mg

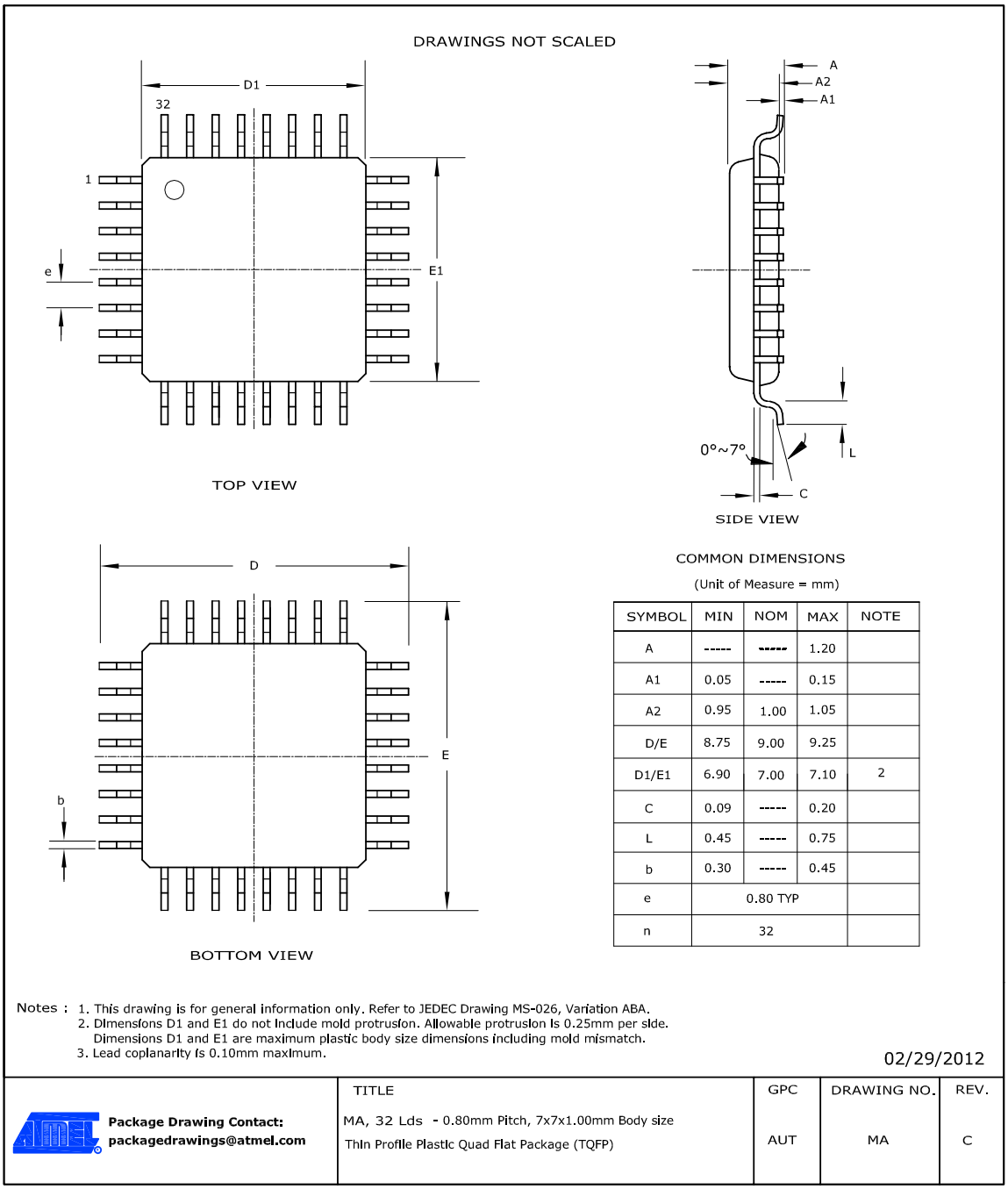
Table 8-3. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-4. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

8.2.2 32 pin TQFP



COMMON DIMENSIONS

(Unit of Measure = mm)

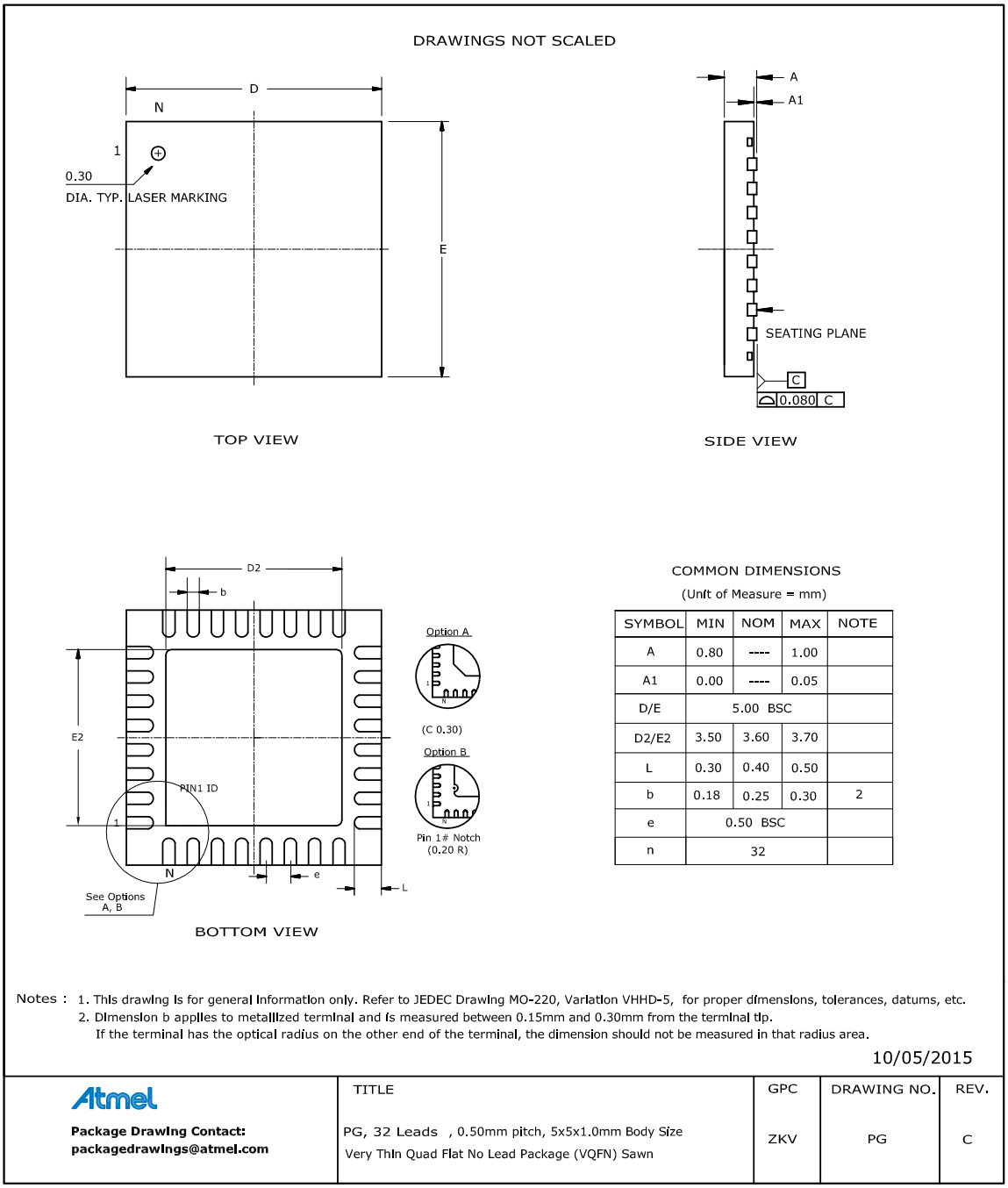
SYMBOL	MIN	NOM	MAX	NOTE
A	-----	-----	1.20	
A1	0.05	-----	0.15	
A2	0.95	1.00	1.05	
D/E	8.75	9.00	9.25	
D1/E1	6.90	7.00	7.10	2
C	0.09	-----	0.20	
L	0.45	-----	0.75	
b	0.30	-----	0.45	
e	0.80 TYP			
n	32			

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MS-026, Variation ABA.
2. Dimensions D1 and E1 do not include mold protrusion. Allowable protrusion is 0.25mm per side. Dimensions D1 and E1 are maximum plastic body size dimensions including mold mismatch.
3. Lead coplanarity is 0.10mm maximum.

02/29/2012

	TITLE	GPC	DRAWING NO.	REV.
Package Drawing Contact: packagedrawings@atmel.com	MA, 32 Lds - 0.80mm Pitch, 7x7x1.00mm Body size Thin Profile Plastic Quad Flat Package (TQFP)	AUT	MA	C

8.2.3 32 pin QFN



COMMON DIMENSIONS

(Unit of Measure = mm)

SYMBOL	MIN	NOM	MAX	NOTE
A	0.80	----	1.00	
A1	0.00	----	0.05	
D/E		5.00 BSC		
D2/E2	3.50	3.60	3.70	
L	0.30	0.40	0.50	
b	0.18	0.25	0.30	2
e		0.50 BSC		
n		32		

Notes : 1. This drawing is for general information only. Refer to JEDEC Drawing MO-220, Variation VHHD-5, for proper dimensions, tolerances, datums, etc.
2. Dimension b applies to metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
If the terminal has the optical radius on the other end of the terminal, the dimension should not be measured in that radius area.

10/05/2015

Atmel **Package Drawing Contact:** **packagedrawings@atmel.com**	TITLE PG, 32 Leads , 0.50mm pitch, 5x5x1.0mm Body Size Very Thin Quad Flat No Lead Package (VQFN) Sawn	GPC ZKV	DRAWING NO. PG	REV. C

Note: The exposed die attach pad is connected inside the device to GND and GNDANA.

Table 8-8. Device and Package Maximum Weight

90	mg

Table 8-9. Package Characteristics

Moisture Sensitivity Level	MSL3

Table 8-10. Package Reference

JEDEC Drawing Reference	MO-220
JESD97 Classification	E3

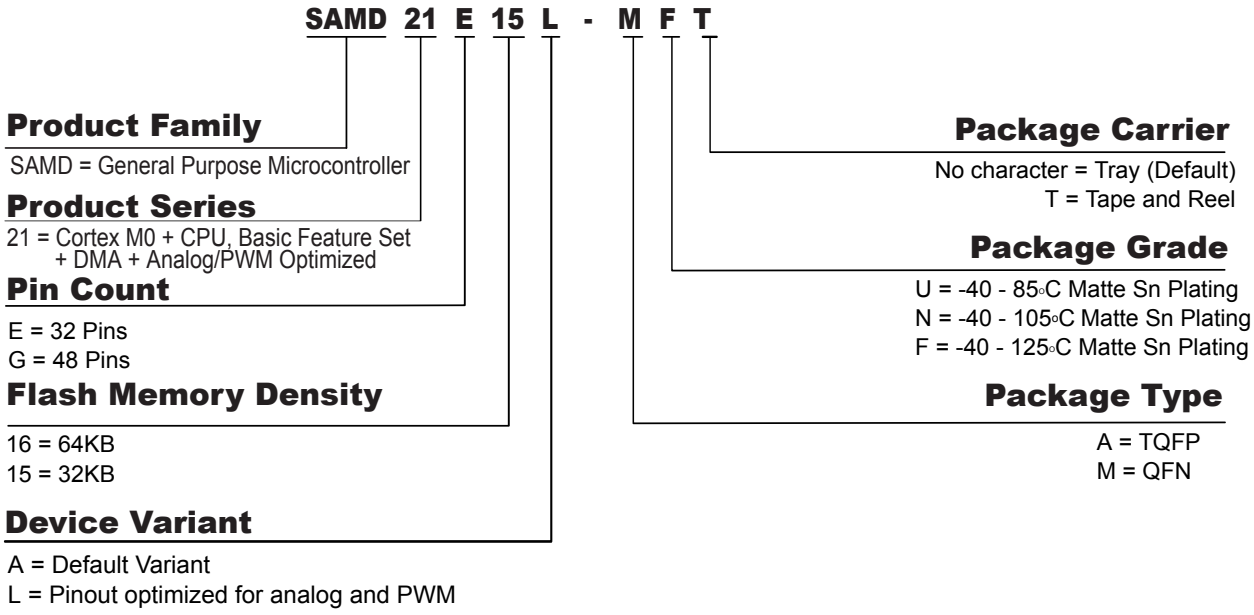
8.3 Soldering Profile

The following table gives the recommended soldering profile from J-STD-20.

Table 8-11.

Profile Feature	Green Package
Average Ramp-up Rate (217°C to peak)	3°C/s max.
Preheat Temperature 175°C ±25°C	150-200°C
Time Maintained Above 217°C	60-150s
Time within 5°C of Actual Peak Temperature	30s
Peak Temperature Range	260°C
Ramp-down Rate	6°C/s max.
Time 25°C to Peak Temperature	8 minutes max.

A maximum of three reflow passes is allowed per component.



Note:

1. Tape and Reel identifier only appears in the catalog part number description. This identifier is used for ordering purposes and is not printed on the device package. Check with your Microchip Sales Office for package availability with the Tape and Reel option.
2. Small form-factor packaging options may be available. Please check http://www.microchip.com/packaging for small-form factor package availability, or contact your local Sales Office.

Microchip Devices Code Protection Feature

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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Quality Management System Certified by DNV

ISO/TS 16949

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.